



**Features**

- Automatic power-down when deselected
- CMOS for optimum speed/power
- High speed
  - 35 ns
- Low active power
  - 660 mW
- Low standby power
  - 110 mW
- TTL-compatible inputs and outputs
- Capable of withstanding greater than 2001V electrostatic discharge

**Functional Description**

The CY6116 is a high-performance CMOS Static RAM organized as 2048 words by 8 bits. Easy memory expansion is provided by an active LOW chip enable ( $\overline{CE}$ ) and active LOW output enable ( $\overline{OE}$ ) and three-state drivers. The CY6116 has an automatic power-down feature, reducing the power consumption by 83% when deselected.

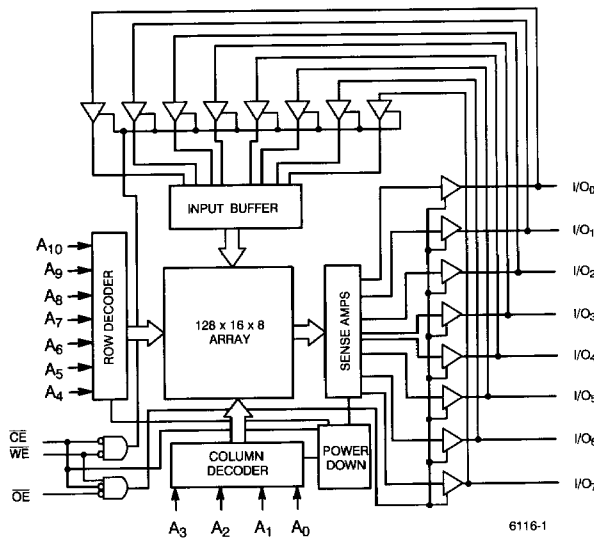
An active LOW write enable signal ( $\overline{WE}$ ) controls the writing/reading operation of the memory. When the chip enable ( $\overline{CE}$ ) and write enable ( $\overline{WE}$ ) inputs are both LOW, data on the eight data input/output pins ( $I/O_0$  through  $I/O_7$ ) is written into the

memory location addressed by the address present on the address pins ( $A_0$  through  $A_{10}$ ). Reading the device is accomplished by selecting the device and enabling the outputs,  $\overline{CE}$  and  $\overline{OE}$  active LOW, while  $\overline{WE}$  remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable ( $\overline{WE}$ ) is HIGH.

The CY6116 utilizes a die coat to insure alpha immunity.

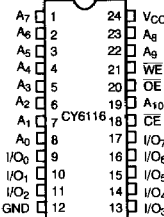
**Logic Block Diagram**



6116-1

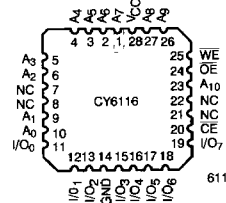
**Pin Configurations**

**DIP/SOJ  
Top View**



6116-2

**LCC  
Top View**



6116-3

**Selection Guide**

		CY6116-35	CY6116-45	CY6116-55
Maximum Access Time (ns)		35	45	55
Maximum Operating Current (mA)	Commercial	120	120	120
	Military	130	130	130
Maximum Standby Current (mA)	Commercial	20	20	20
	Military	20	20	20

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

- Storage Temperature ..... - 65°C to + 150°C
- Ambient Temperature with Power Applied ..... - 55°C to + 125°C
- Supply Voltage to Ground Potential (Pin 24 to Pin 12) ..... - 0.5V to + 7.0V
- DC Voltage Applied to Outputs in High Z State ..... - 0.5V to + 7.0V
- DC Input Voltage ..... - 3.0V to + 7.0V
- Output Current into Outputs (Low) ..... 20 mA

- Static Discharge Voltage ..... > 2001V (per MIL-STD-883, Method 3015)
- Latch-Up Current ..... > 200 mA

**Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0°C to + 70°C	5V ± 10%
Military <sup>[1]</sup>	- 55°C to + 125°C	5V ± 10%

**Electrical Characteristics Over the Operating Range<sup>[2]</sup>**

Parameters	Description	Test Conditions	CY6116		Units
			Min.	Max.	
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = - 4.0 mA	2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.0	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage		-3.0	0.8	V
I <sub>IX</sub>	Input Load Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub>	-10	+10	µA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub> , Output Disabled		+10	µA
I <sub>OS</sub>	Output Short Circuit Current <sup>[3]</sup>	V <sub>CC</sub> = Max., V <sub>OUT</sub> = GND		-300	mA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA	Com'l	120	mA
			Mil	130	
I <sub>SB</sub>	Automatic CE Power-Down Current	Max. V <sub>CC</sub> , $\overline{CE} \geq V_{IH}$	Com'l	20	mA
			Mil	20	

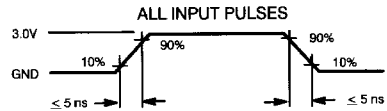
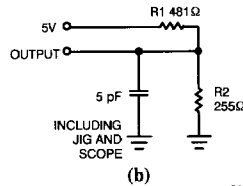
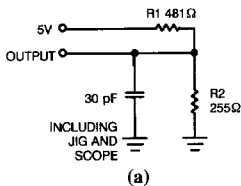
**Capacitance<sup>[4]</sup>**


Parameters	Description	Test Conditions	Max.	Units
C <sub>IN</sub>	Input Capacitance	T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 5.0V	10	pF
C <sub>OUT</sub>	Output Capacitance		10	pF

**Notes:**

1. T<sub>A</sub> is the "instant on" case temperature.
2. See the last page of this specification for Group A subgroup testing information.
3. Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
4. Tested initially and after any design or process changes that may affect these parameters.

**AC Test Loads and Waveforms**



Equivalent to: THEVENIN EQUIVALENT  


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**Switching Characteristics** Over the Operating Range<sup>[2,5]</sup>

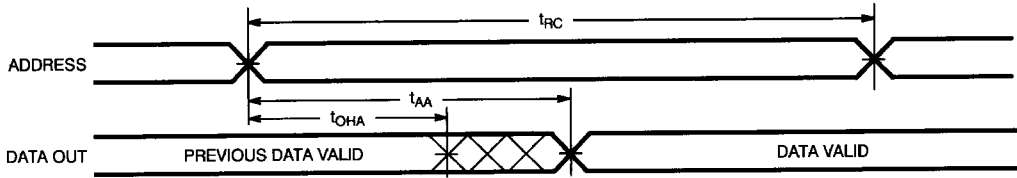
Parameters	Description	CY6116-35		CY6116-45		CY6116-55		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>READ CYCLE</b>								
t <sub>RC</sub>	Read Cycle Time	35		45		55		ns
t <sub>AA</sub>	Address to Data Valid		35		45		55	ns
t <sub>OHA</sub>	Data Hold from Address Change	5		5		5		ns
t <sub>ACE</sub>	$\overline{CE}$ LOW to Data Valid		35		45		55	ns
t <sub>DOE</sub>	$\overline{OE}$ LOW to Data Valid		15		20		25	ns
t <sub>LZOE</sub>	$\overline{OE}$ LOW to Low Z	0		0		0		ns
t <sub>HZOE</sub>	$\overline{OE}$ HIGH to High Z <sup>[6]</sup>		15		15		20	ns
t <sub>LZCE</sub>	$\overline{CE}$ LOW to Low Z <sup>[7]</sup>	5		5		5		ns
t <sub>HZCE</sub>	$\overline{CE}$ HIGH to High Z <sup>[6,7]</sup>		15		20		20	ns
t <sub>PU</sub>	$\overline{CE}$ LOW to Power-Up	0		0		0		ns
t <sub>PD</sub>	$\overline{CE}$ HIGH to Power-Down		20		25		25	ns
<b>WRITE CYCLE<sup>[8]</sup></b>								
t <sub>WC</sub>	Write Cycle Time	35		45		55		ns
t <sub>SCE</sub>	$\overline{CE}$ LOW to Write End	30		40		40		ns
t <sub>AW</sub>	Address Set-Up to Write End	30		40		40		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		0		ns
t <sub>PWE</sub>	$\overline{WE}$ Pulse Width	20		20		25		ns
t <sub>SD</sub>	Data Set-Up to Write End	15		20		25		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		0		ns
t <sub>HZWE</sub>	$\overline{WE}$ LOW to High Z <sup>[6]</sup>		15		15		20	ns
t <sub>LZWE</sub>	$\overline{WE}$ HIGH to Low Z	0		0		0		ns

**Notes:**

5. Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/A<sub>OH</sub> and 30-pF load capacitance.
6. t<sub>HZOE</sub>, t<sub>HZCE</sub>, and t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady state voltage.
7. At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> for any given device.
8. The internal write time of the memory is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{WE}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
9.  $\overline{WE}$  is HIGH for read cycle.
10. Device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}$  = V<sub>IL</sub>.
11. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.
12. Data I/O pins enter high-impedance state, as shown, when  $\overline{OE}$  is held LOW during write.
13. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high-impedance state.

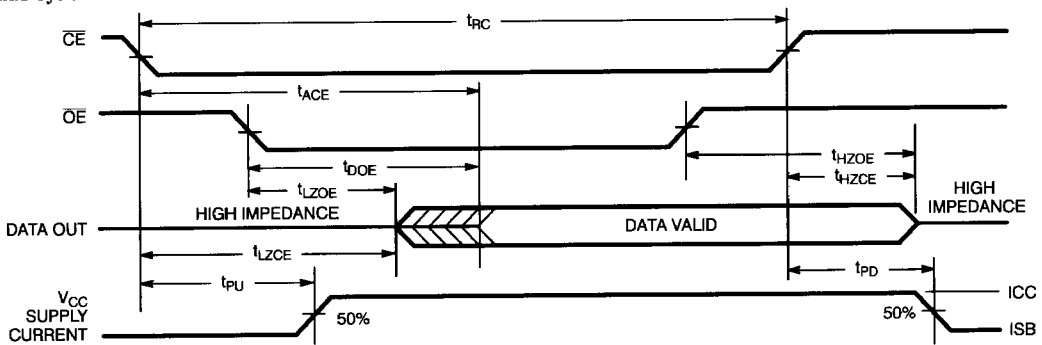
Switching Waveforms

Read Cycle No. 1<sup>[9,10]</sup>



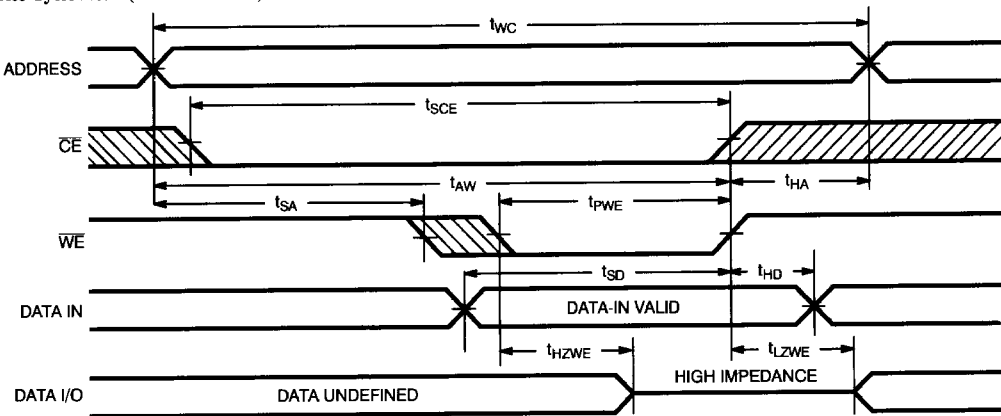
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Read Cycle No. 2<sup>[9,11]</sup>



6116-7

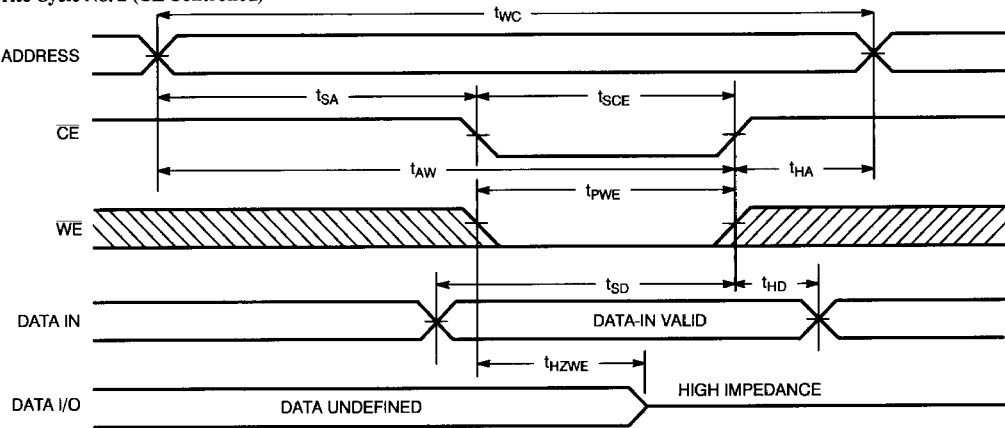
Write Cycle No. 1 ( $\overline{WE}$  Controlled)<sup>[9,12]</sup>



6116-8

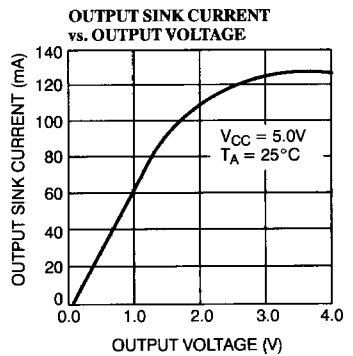
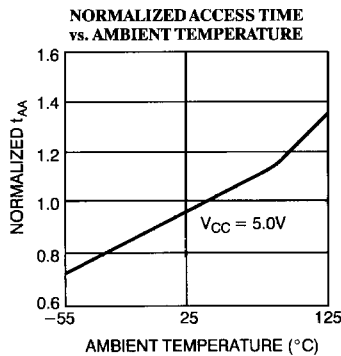
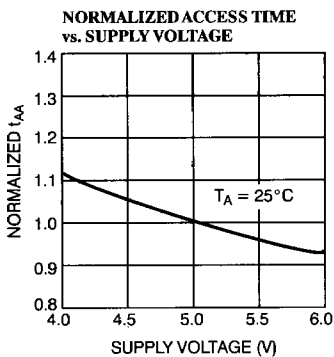
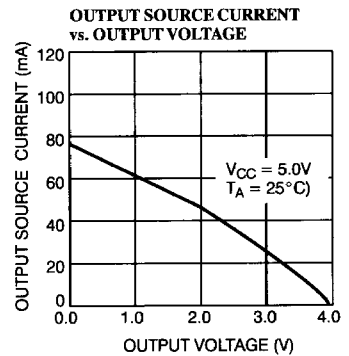
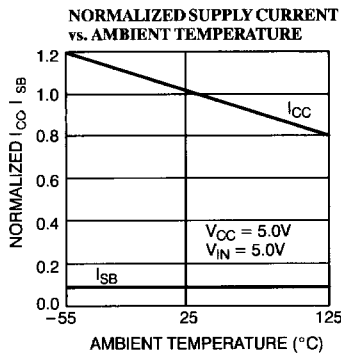
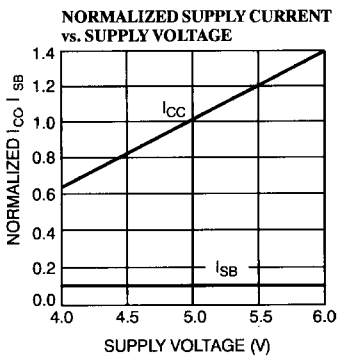
Switching Waveforms (continued)

Write Cycle No. 2 (CE Controlled)<sup>[8,12,13]</sup>

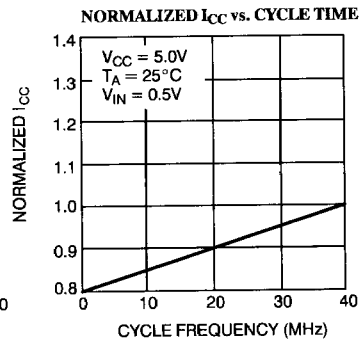
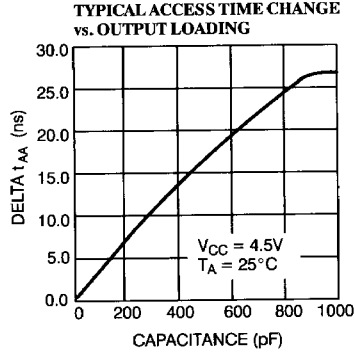
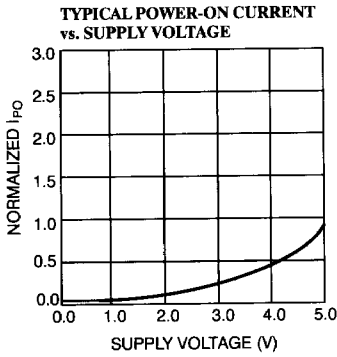


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Typical DC and AC Characteristics



Typical DC and AC Characteristics (continued)



Ordering Information

Speed (ns)	Ordering Code	Package Type	Operating Range
35	CY6116-35PC	P11	Commercial
	CY6116-35DC	D12	
	CY6116-35LC	L64	
	CY6116-35DMB	D12	Military
	CY6116-35LMB	L64	
45	CY6116-45PC	P11	Commercial
	CY6116-45DC	D12	
	CY6116-45LC	L64	
	CY6116-45DMB	D12	Military
	CY6116-45LMB	L64	
55	CY6116-55PC	P11	Commercial
	CY6116-55DC	D12	
	CY6116-55LC	L64	
	CY6116-55DMB	D12	Military
	CY6116-55LMB	L64	

**MILITARY SPECIFICATIONS**
**Group A Subgroup Testing**
**DC Characteristics**

Parameters	Subgroups
$V_{OH}$	1, 2, 3
$V_{OL}$	1, 2, 3
$V_{IH}$	1, 2, 3
$V_{IL, Max.}$	1, 2, 3
$I_{IX}$	1, 2, 3
$I_{OZ}$	1, 2, 3
$I_{CC}$	1, 2, 3
$I_{SB}$	1, 2, 3

**Switching Characteristics**

Parameters	Subgroups
<b>READ CYCLE</b>	
$t_{RC}$	7, 8, 9, 10, 11
$t_{AA}$	7, 8, 9, 10, 11
$t_{OHA}$	7, 8, 9, 10, 11
$t_{ACE}$	7, 8, 9, 10, 11
$t_{DOE}$	7, 8, 9, 10, 11
<b>WRITE CYCLE</b>	
$t_{WC}$	7, 8, 9, 10, 11
$t_{SCE}$	7, 8, 9, 10, 11
$t_{AW}$	7, 8, 9, 10, 11
$t_{HA}$	7, 8, 9, 10, 11
$t_{SA}$	7, 8, 9, 10, 11
$t_{PWE}$	7, 8, 9, 10, 11
$t_{SD}$	7, 8, 9, 10, 11
$t_{HD}$	7, 8, 9, 10, 11

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